



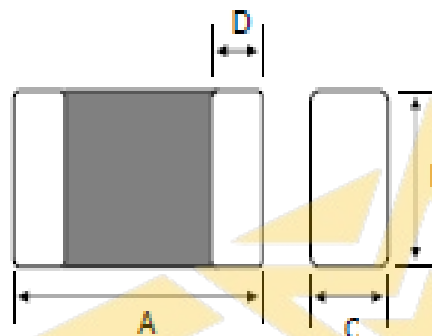
Physical Dimensions : mm (inch)

A = 2.0 ± 0.2 (0.079 \pm 0.008)

B = 1.2 ± 0.2 (0.047 \pm 0.008)

C = 0.9 ± 0.2 (0.035 \pm 0.008)

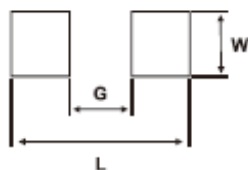
D = 0.5 ± 0.3 (0.020 \pm 0.012)



General Information :

1. Termination Finish is 100% Tin.
2. Components Should be Adequately Preheated Before Soldering.
3. Operating Temperature: -55°C to +125°C
4. Storage Temperature (on Tape & Reel): 40°C MAX. , 70% RH

Land Patterns for Reflow Soldering



L	W	G
3.20(0.126)	1.50(0.059)	0.60(0.024)

Packing Method:

One reel = 4,000 pcs

One Box = 200,000 pcs

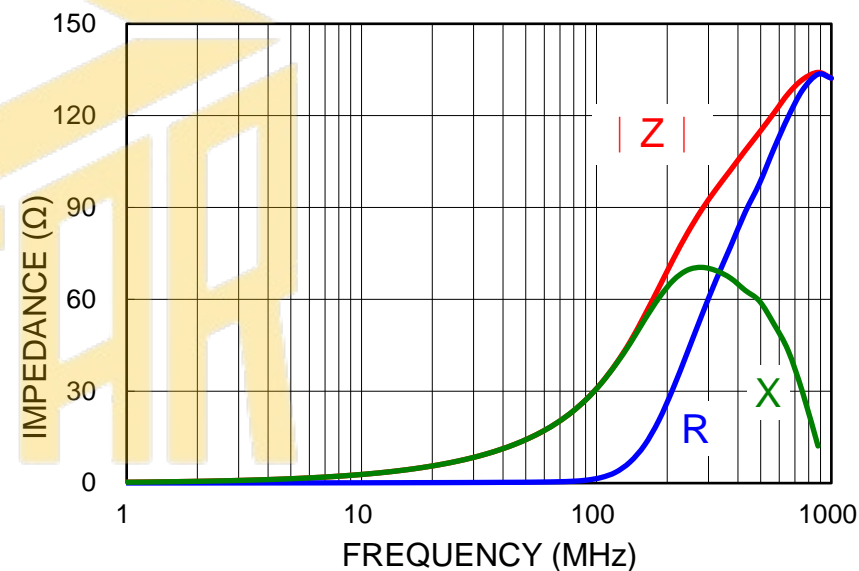
One Box = 10.3 KG

Electrical Characteristics :

	Value	Unit	Tolerance	Test Condition
Impedance	30	Ω	$\pm 25\%$	100MHz / 100mV
DCR	0.15	Ω	Max.	
IDC	400	mA	Max.	

Typical Impedance Characteristics : HP 4291B

TB201209B300



Multilayer Ferrite Chip Beads

P/N

TB 201209 B300

Version

N000

N000
VER.

Initial
DESCRIPTION

DATE

BY



+886-3-4962286
www.tecstar.com.tw